



Quartz Crystal

SEAM SEALED CERAMIC 6 X 3.5MM 2 PADS Surface Mount Package

FEATURE

- I Leadless type.
- I Automatic mounting.
- I Rugged AT-cut crystal construction
- I Emboss taping specification.
- I Suitable for solder Reflow.
- I Available on tape and reel ,1000pcs per reel
- I Lead Free & RoHS Compliant

APPLICATIONS

- I Ideally suited designed for disc drives, NB, PCs and hand-held electronic products

ELECTRICAL SPECIFICATIONS

Output Frequency Range	8.000MHz to 80.000MHz
Mode	See Table 1
Frequency Tolerance (at 25°C)	±30ppm, ±50ppm, or specify
Frequency Stability Over Operating Temperature Characteristics	±30ppm, ±50ppm or specify
Storage Temperature Range	-55 °C to +125 °C
Operating Temperature Range	-10 °C to + 60 °C, -20 °C to + 70 °C, -40 °C to + 85 °C,
Shunt Capacitance (C ₀)	5.0 pF Max
Driver Level (Typical)	10µW
Load Capacitance(C _L)	Series, 16pF, 20pF, 30pF, 32pF, or specify
Equivalent Series Resistance ESR (Ω)	See Table 1
Aging @25°C 1 st year (Max)	±3ppm/year
Shock Resistance	Drop test of 3 times on 2mm stainless plate from 75cm height

REMARK: SPECIFICATIONS SUBJECT TO CHANGE WITHOUT PRIOR NOTICE. PLEASE CONFIRM WITH OUR SALES ENGINEER.

Frequencies and Equivalent Series Resistant

Frequency Range	E.S.R. (Ω)	Mode
8.000 MHz ~ 10.000 MHz	70 Max	Fundamental / AT
10.000 MHz ~ 30.000 MHz	40 Max	Fundamental / AT
30.000 MHz ~ 45.000 MHz	60 Max	Third Overtone / AT
45.000 MHz ~ 80.000 MHz	50 Max	Third Overtone / AT

PART NUMBER

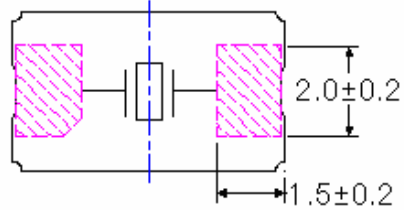
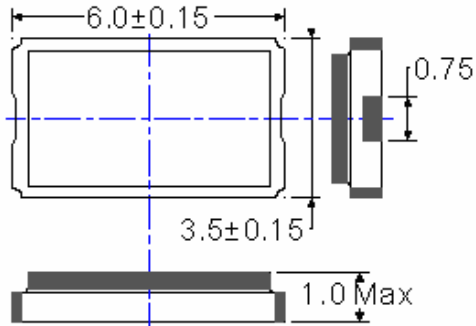
SJK-	13.560	16	30	40	A	50
6G2-	Frequency	Load capacitance e.g. 16: 16pf s: series	Frequency tolerance e.g. 30: ±30ppm	E.S.R.max e.g. 40:40Ωmax	Operating temperature range A:-10-60°C B:-20-70°C C:-40-85°C	Temperature stability: e.g. 50: ±50ppm

The design, manufacturing process, and specifications of this device are subject to change without notice.

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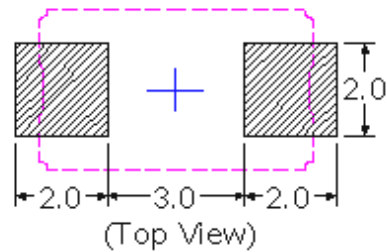
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Dimension



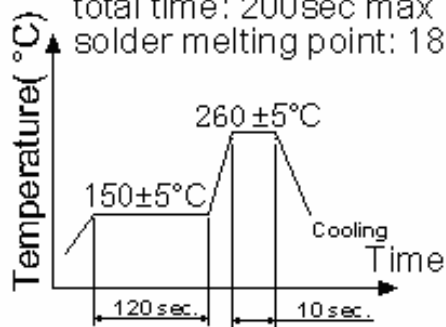
Connection and Pad
(Top View)

Reference Land Pattern



Reflow Condition

total time: 200sec max
solder melting point: 185°C



PACKING

